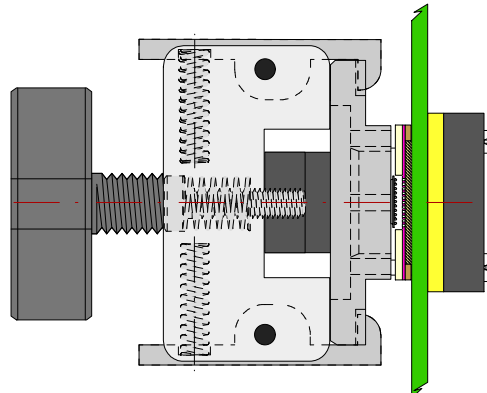
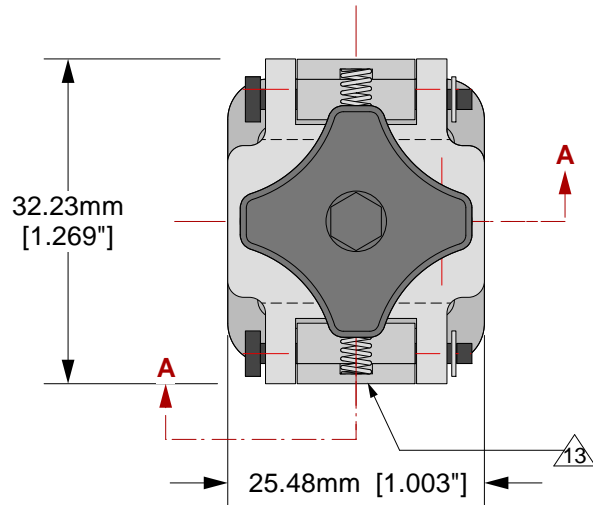
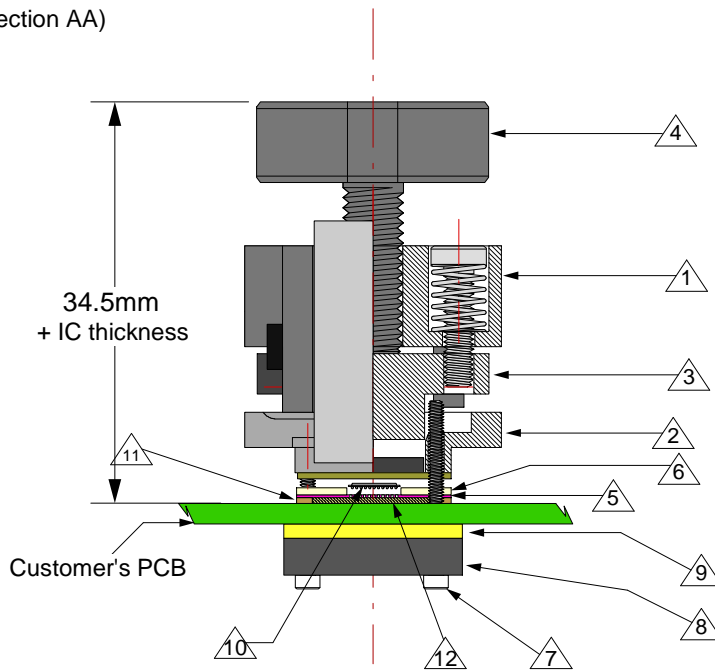


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

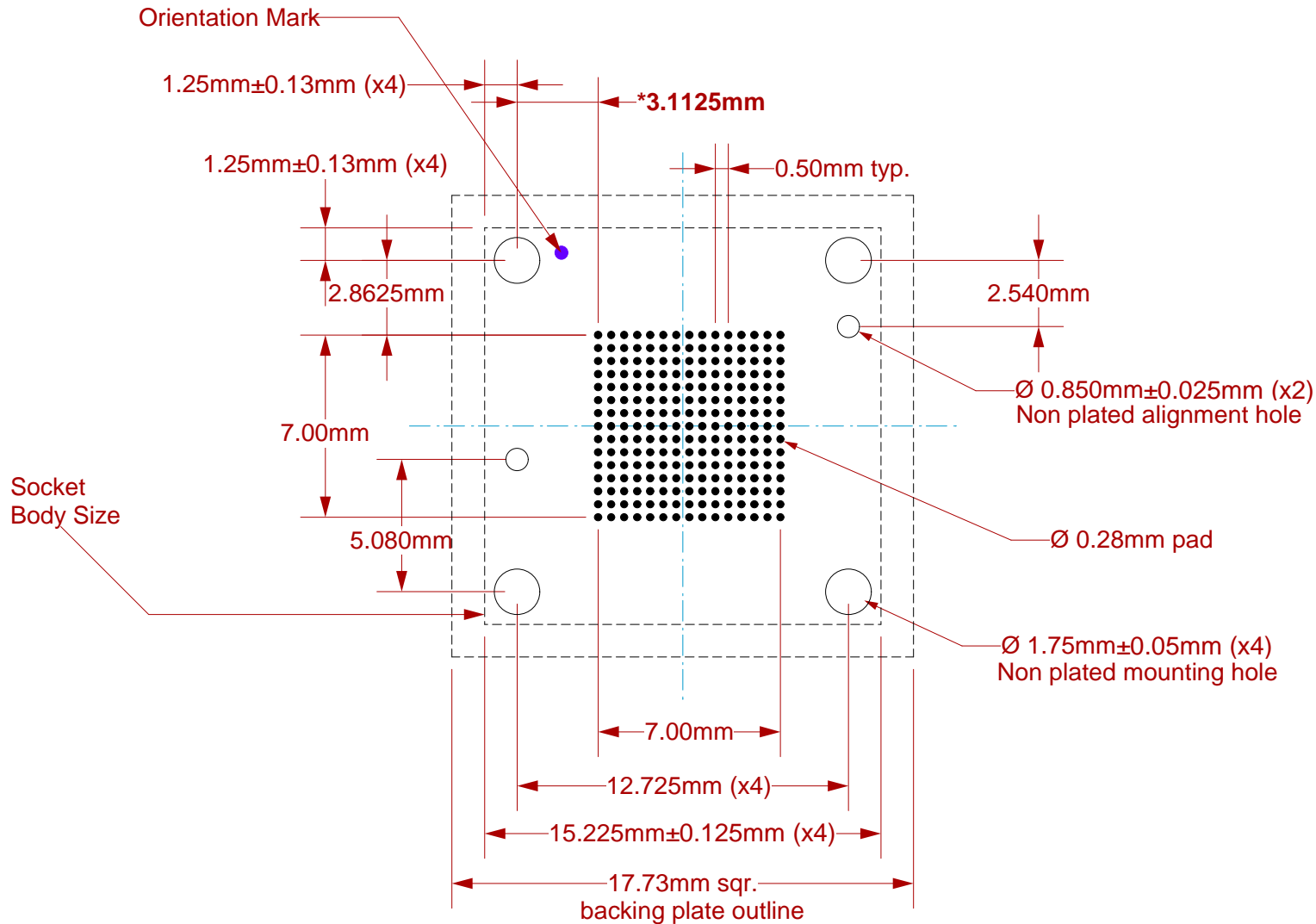
- △1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- △4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- △5 Ball Guide: Kapton polyimide.
- △6 IC Guide: Torton
- △7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- △8 Backing Plate: Black anodized Aluminum. Thickness= 4mm
- △9 Insulation Plate: FR4/G10
- △10 Customer's BGA IC
- △11 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △12 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △13 Latch: Black anodized Aluminum.

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

 <p>CG-BGA-5002 Drawing © 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale: -	Rev: B
	Drawing: J. Glab		Date: 9/13/07
	File: CG-BGA-5002 Dwg.mcd		Modified: 09/17/14 , DH

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

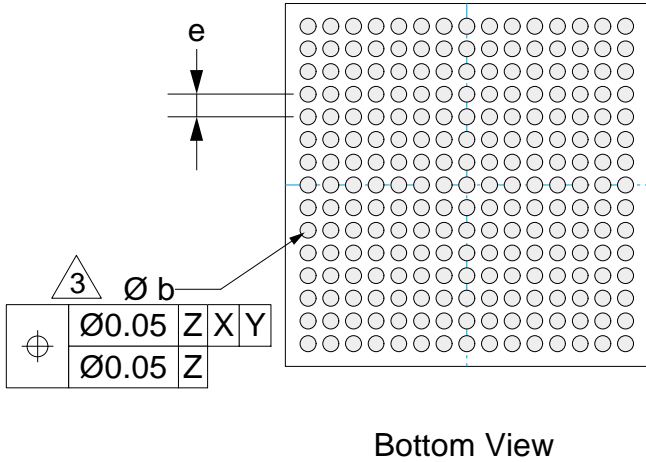
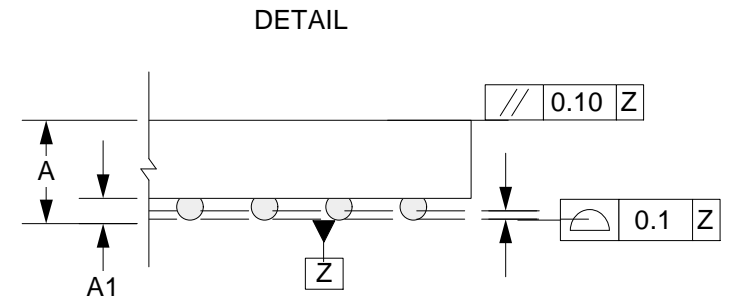
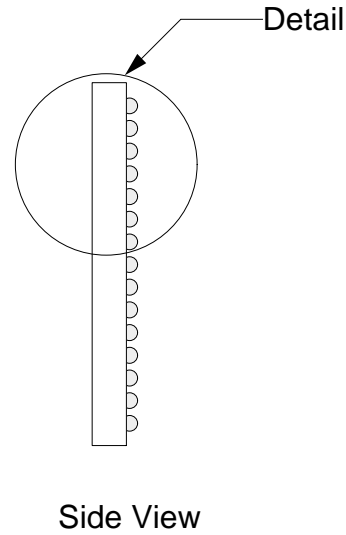
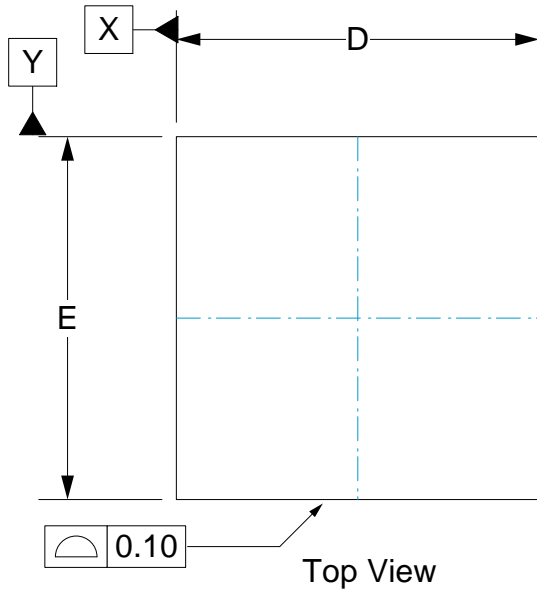
Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

Recommended PCB Layout Tolerances:
 ±0.025mm [±0.001"] unless stated otherwise.
 All dimensions are in mm.


	CG-BGA-5002 Drawing	Status: Released	Scale: 4:1	Rev: B
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		File: CG-BGA-5002 Dwg.mcd	Modified: 09/17/14, DH	

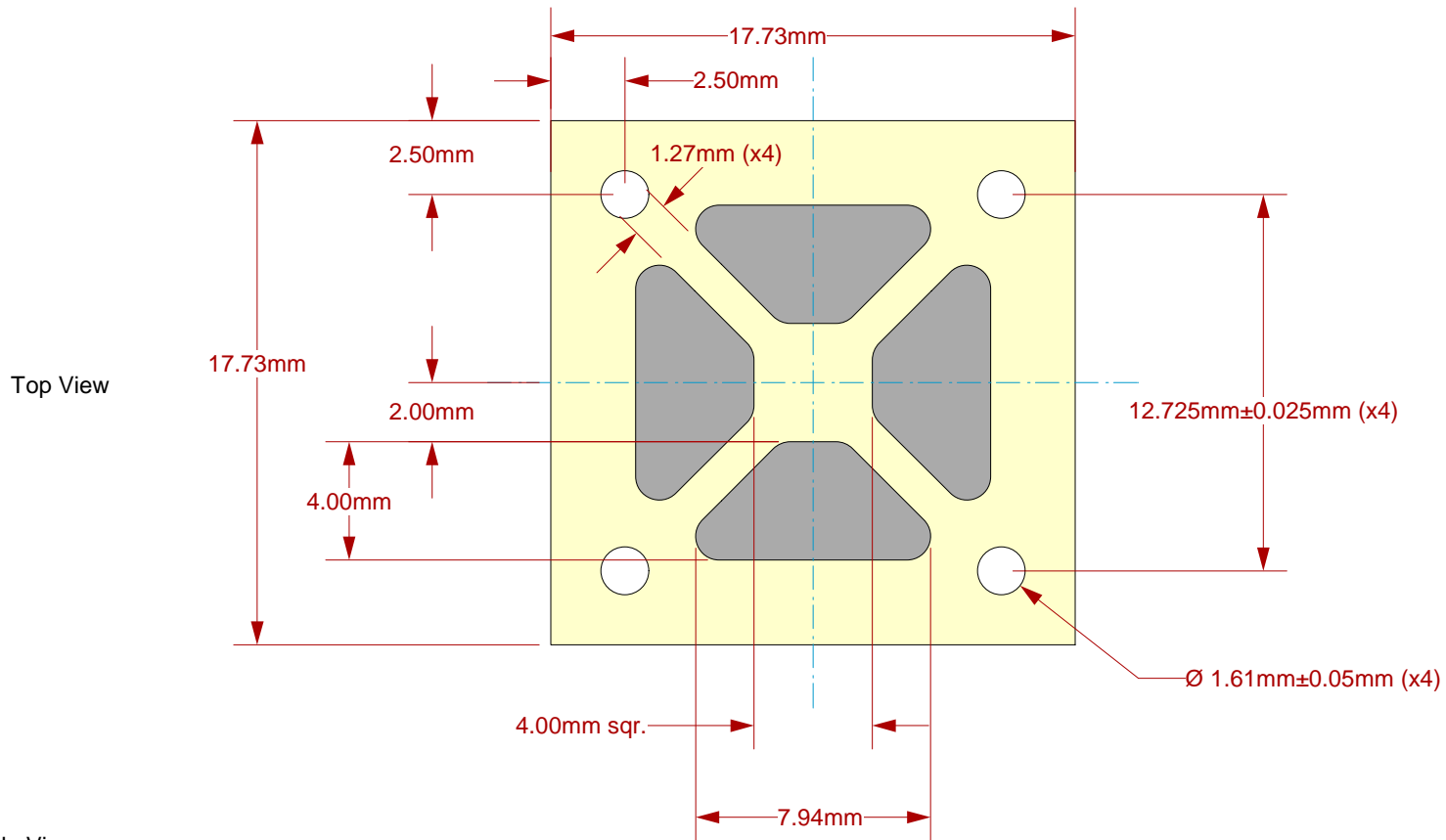


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

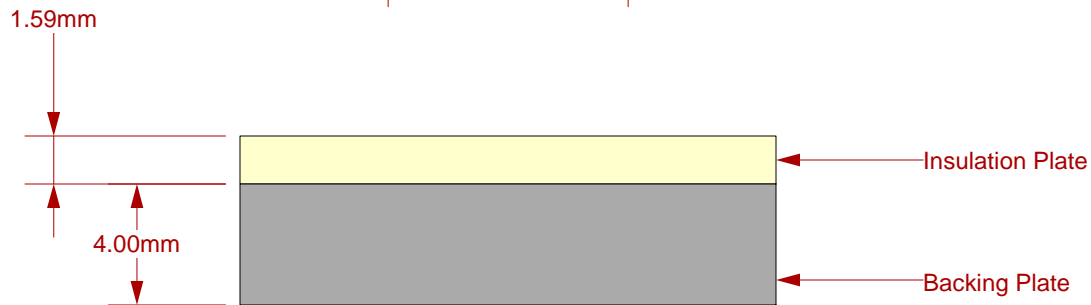
DIM	MIN	MAX
A	0.74	1.0
A1	0.18	0.28
b	0.29	0.35
D	8.0 BSC	
E	8.0 BSC	
e	0.5 BSC	

15 x 15 array

 <p>CG-BGA-5002 Drawing © 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale: -	Rev: B
	Drawing: J. Glab		Date: 9/13/07
	File: CG-BGA-5002 Dwg.mcd		Modified: 09/17/14, DH



Side View




Description: Backing Plate with Insulation Plate

USE DXF DATA

PAGE 4 of 4

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

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		Drawing: J. Glab	Date: 9/13/07	
		File: CG-BGA-5002 Dwg.mcd	Modified: 09/17/14, DH	